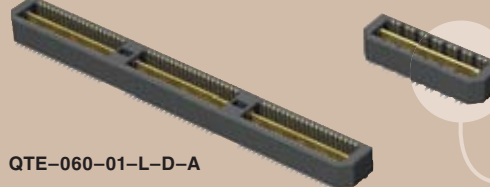




(0,80mm) .0315"

QTE SERIES

QTE-014-01-F-D-DP-A



QTE-014-01-L-D-A-RT1

HIGH SPEED GROUND PLANE HEADER

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com/QTE

Insulator Material:

Liquid Crystal Polymer



Terminal Material:

Phosphor Bronze



Plating:

Au or Sn over 50µ" (1,27µm) Ni

Current Rating:

Contacts: 1.3A @ 95°C

Ground Plane: 10.1A @ 95°C

Operating Temp Range:

-55°C to +125°C

Voltage Rating:

225 VAC mated with QSE & 5mm Stack Height

Max Cycles: 100

Unmating Force (-RT1 option):

-RT1 option increases unmating force up to 50%

RoHS Compliant:

Yes

Processing:

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0,10mm) .004" max (020-060)

(0,15mm) .006" max (080)

Board Stacking:

For applications requiring more than two connectors per board or 4 banks or more, contact ipg@samtec.com

APPLICATION SPECIFIC OPTION

- 14mm, 15mm, 22mm and 30mm stack height (Caution: Some automatic placement/inspection machines may have component height restrictions. Please consult machinery specifications.)
- 30µ" (0,76µm) Gold (Specify -H plating for Data Rate cable mating applications.)
- Edge Mount
- 100 positions per row
- Guide Posts, Screw Down & Friction Lock
- Call Samtec.

*Note: -C Plating passes 10 year MFG testing

Note: Some lengths, styles and options are non-standard, non-returnable.

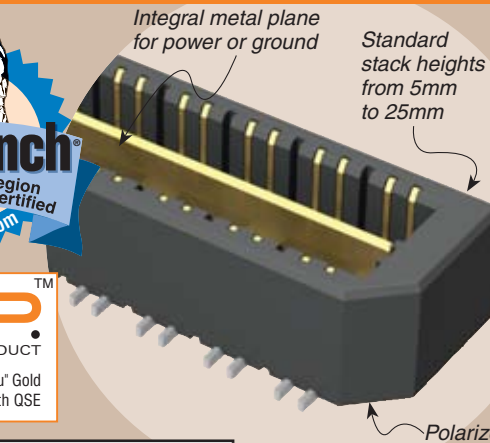
Board Mates: QSE

Cable Mates: EQCD, EQSD, EQDP, EQRF (See Application Specific note)

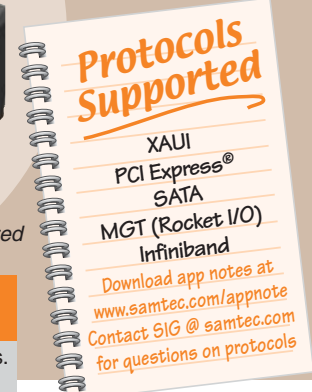


5mm Stack Height	Type	Rated @ 3dB Insertion Loss
Single-Ended Signaling	-D	9 GHz / 18 Gbps
Differential Pair Signaling	-D	8 GHz / 16 Gbps
Differential Pair Signaling	-DP	8.5 GHz / 17 Gbps

Performance data for other stack heights and complete test data available at www.samtec.com/QTE or contact sig@samtec.com



- E.L.P.™ plating option (-C)
- Retention pin option

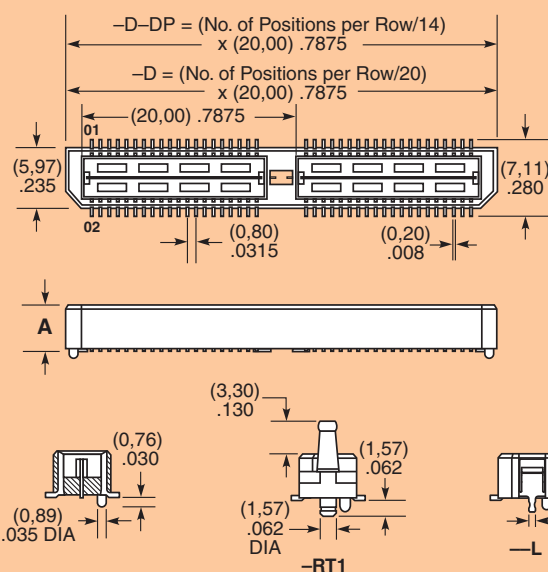


ALSO AVAILABLE
Board Spacing Standoffs. See SO Series.

QTE	PINS PER ROW NO. OF PAIRS	LEAD STYLE	PLATING OPTION	TYPE	A	OTHER OPTION
	-020, -040, -060, -080 (40 total pins per bank = -D)	Specify LEAD STYLE from chart	-F = Gold Flash on Signal Pins and Ground Plane, Matte Tin on tails	-D = Single-Ended	-D-DP = Differential Pair (-01 only)	-K = (7,00mm) .275" DIA Polyimide Film Pick & Place Pad
	-014, -028, -042, -056 (14 pairs per bank = -D-DP)		-L = 10µ" (0,25µm) Gold on Signal Pins and Ground Plane, Matte Tin on tails			-TR = Tape & Reel Packaging (N/A on 56 & 80 positions or -05 & -07 lead style)
			-C* = Electro-Polished Selective 50µ" (1,27µm) min Au over 150µ" (3,81µm) Ni on Signal Pins in contact area, 10µ" (0,25µm) min Au over 50µ" (1,27µm) Ni on Ground Plane in contact area, Matte Tin over 50µ" (1,27µm) min Ni on all solder tails			-RT1 = Retention Option (-01 Lead Style only) (N/A on 56 & 80 positions or -L (latch) option)
						-L = Latching Option (N/A on 42, 56, 60 & 80 positions or -RT1 option)

QTE LEAD STYLE	A	HEIGHT WITH QSE*
-01	(4,27) .168	(5,00) .197
-02	(7,26) .286	(8,00) .315
-03	(10,27) .404	(11,00) .433
-04	(15,25) .600	(16,00) .630
-05	(18,26) .718	(19,00) .748
-07	(24,24) .954	(25,00) .984

*Processing conditions will affect mated height.



Due to technical progress, all designs, specifications and components are subject to change without notice.

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